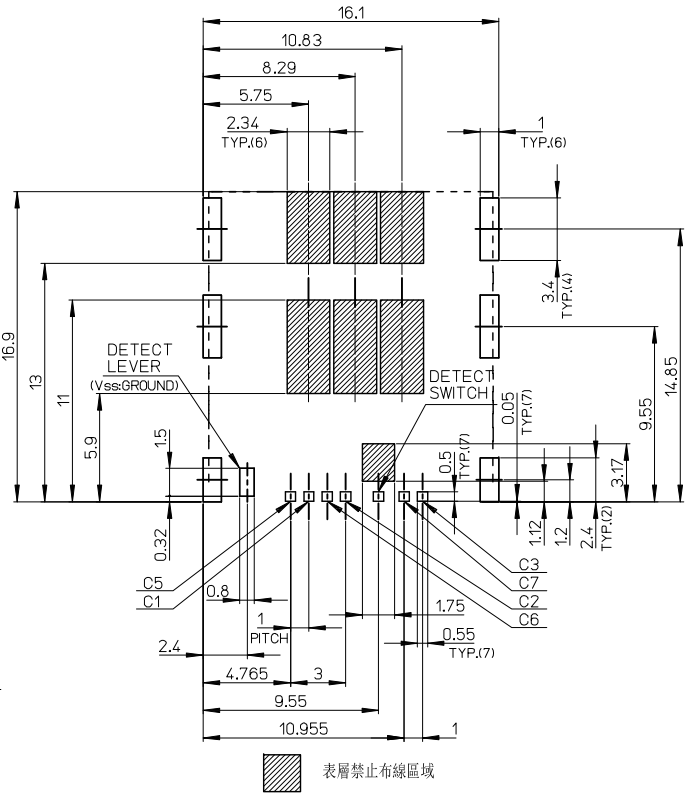
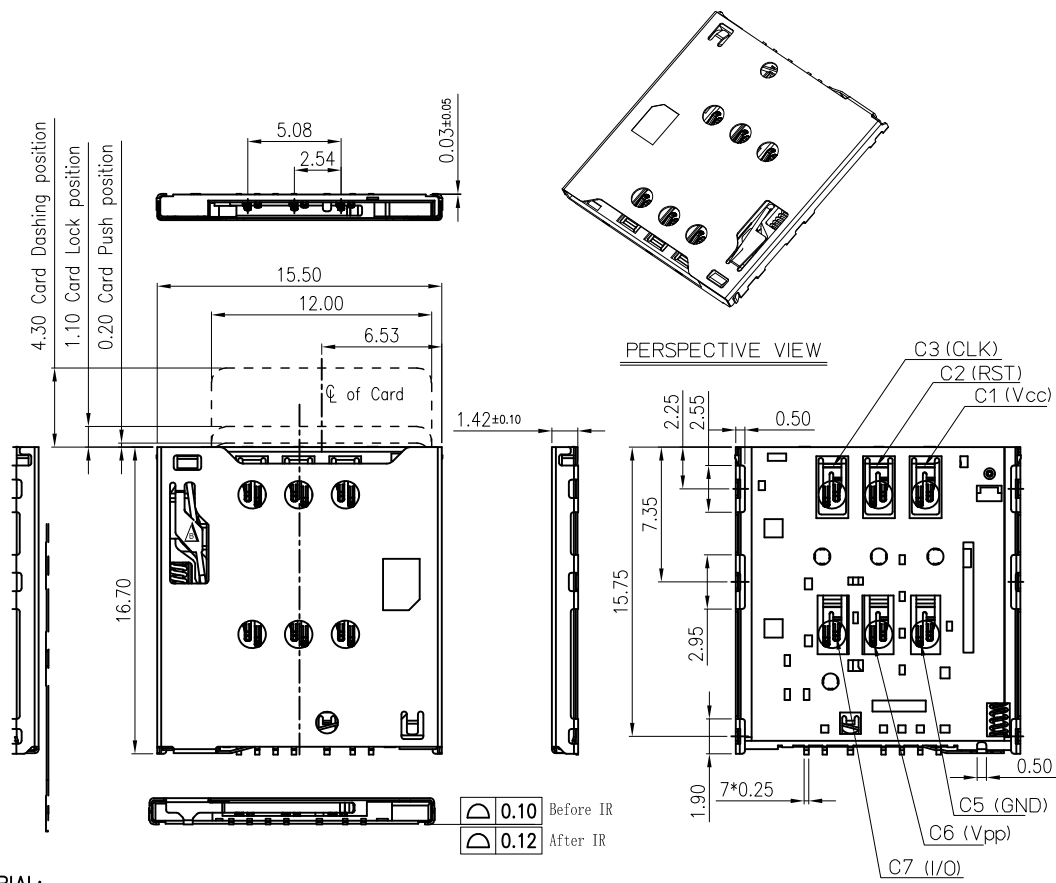


更改 REV	變更內容 MODIFICATION
A	EC06509
B	EC06824
C	EC07125

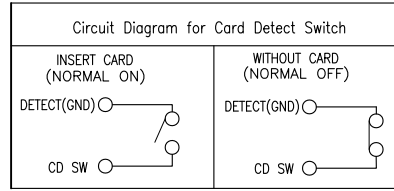


RECOMMENDED PCB PATTERN LAYOUT  
(GENERAL TOLERANCE : ±0.05)

**MATERIAL:**  
 Insulator: High Temperature Thermoplastic, UL 94-0.  
 Contact: Copper Alloy.  
 SHELL: SUS.

**PLATING:**  
 Contact: Plated 50u" Ni Overall Contact Au 1u".  
 Shell: Plated 50u" Ni Overall Plated 1u" Au  
 Selective Contact Area.

**Electrical:**  
 Current Rating: 0.5A AC/DC max.  
 Voltage Rating: 125V AC/DC.  
 ▲DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE.  
 ▲Storage Temperature Range: -40°C~+85°C.  
 ▲Operation Temperature Range: -40°C~+85°C.  
 Ambient Humidity Range: 95% R.H. Max.  
 Contact Resistance: 100mΩ max.  
 Insulation Resistance: 1minute 500VDC.  
 High temperature resistant: 260°  
 Mating Cycles: 5000Min Insertions.



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X.± 0.50	X.± 5	名廠(TITLE) Micro sim push H1.42mm	
.X± 0.30	.X± 2		
.XX± 0.20	.XX± 1		
單位(UNIT) mm	料號(PART NO.) 7SIMC-F0-0041	圖號(DWG NO.) 7SIMC-F0-0041-C	比例(SCALE) 1:1
審核(APPROVAL)	核對(CHECKED)	製圖(DRAWN)	張數(SHEET) 1/1
			更改(REV) C

